## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2021 to Q4/2021

Based on structural	similarity
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Supplier		User Part Number						
Nexperia B.V.		PTVS13VP1UTP						
Name of Laboratory		Part Description						
		Nexperia DHAM	Protection					
Assembly reliability labs		SMD package						
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113 Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = $85 ^{\circ}$ C, RH = $85\%$	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	286	21480	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A						
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage	1000 hours	117	9360	0		
	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C						
# A4	Temperature Cycling		1000 cycles	86	6880	0		
	AC	JESD22-A102 Tamb = 121 °C, RH = 100 %						
# A3 alt	Autoclave	Pressure = $205 \text{ kPa} (29.7 \text{ psia})$	96 hours	86	6880	0		
# AS all		······	50 110013	00	0000	0		
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	86	6880	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =						
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
		150500 4444						
# 60	<b>RSH</b> Resistance to Solder Heat	JESD22-A111	10 -	20	0.40	0		
# C8			10 s	28	840	0		
# C10	<b>SD</b> Solderability	J-STD-002		36	360	0		
	,	by test chamber set up and does not exceed		30	200	U		

[1]The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Protection	9360	0	0.45	2.20E+09

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